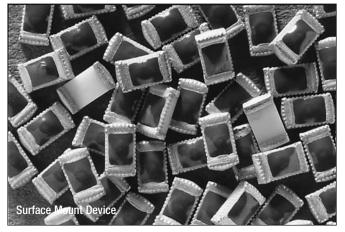
# COOPER **Bussmann**<sup>®</sup>

# 0603ESDA-TR ESD Suppressor **PolySurg**<sup>™</sup> TR Series





## Description

The PolySurg™ 0603ESDA-TR ESD Suppressors protect valuable high-speed data circuits from ESD damage without distorting data signals as a result of its ultra-low (0.15pF maximum) capacitance.

#### Features

- 0603/1608 footprint surface mount device
- Ideal ESD protection for high frequency, low voltage applications.
- Provides ESD protection with fast response time (<1ns) allowing</li> equipment to pass IEC 61000-4-2 testing
- · Very low leakage current
- Ultra low capacitance (0.15pF maximum)
- · Bi-directional

Specifications							
Performance Characteristics	Units Min		Тур	Max			
Continuous operating voltage	Vdc	-	-	24			
Clamping voltage <sup>2</sup>	V	-	35	60			
Trigger voltage3	V	-	125	-			
ESD Threat voltage capability <sup>₄</sup>	kV	-	8	15			
Capacitance (@ 1KHz ~ 1.8GHz)	pF	-	-	0.15			
Leakage current (@ 12Vdc)	nA	0.01	<0.1	-			
Peak current <sup>2</sup>	А	-	30	45			
Operating temperature	°C	-56	+25	+105			
ESD pulse withstand <sup>2</sup>	# pulses	20	>5001	-			

1. Some shifting in characteristics may occur when tested over several hundred ESD pulses at very rapid rate of 1 pulse per second or faster.

2. Per IEC 61000-4-2, 30A @ 8kV, level 4, clamp measurement made 30ns after initiation of pulse, all tests in contact discharge mode.

3. Trigger measurement made using Transmission Line Pulse (TLP) method.

4. PolySURG<sup>™</sup> devices are capable of withstanding up to a 15kV, 45A ESD pulse. Device ratings are given at 8kV per Note 1, unless otherwise specified.

# Applications

- Computers and peripherals HDTV Equipment • DVD Players
- PDAs
- Digital camcorders
- Set Top Boxes

Satellite radio

- Infiniband®

- A/V Equipment
- Cell phones
- Digital still cameras
- MP3 / Multimedia players
- External Storage
- DSL Modems
- High speed data ports
- USB 2.0/3.0
- High speed ethernet

- IEEE 1394 - DVI
- HDMI

#### Packaging

• 5,000 pieces in paper tape on 7 inch diameter (178mm) reel.

**Ordering Information** 

Catalog Number	Description
I UUUJEJDA-INI	5,000 pieces in paper tape on 7 inch diameter (178mm) reel.

# **Device Marking**

PolySurg<sup>™</sup> ESD Suppressors are marked on the tape and reel packages, not individually. Since the product is bi-directional and symmetrical, no orientation marking is required.

# **Design Consideration**

The location in the circuit for the TR series has to be carefully determined. For better performance, the device should be placed as close to the signal input as possible and ahead of any other component. Due to the high current associated with an ESD event, it is recommended to use a "0-stub" pad design (pad directly on the signal/data line and second pad directly on common ground).

## Processing Recommendations

The TR series currently has a convex profile on the top surface of the part. This profile is a result of the construction of the deice. They can be processed using standard pick-and-place equipment. The placement and processing techniques for these devices are similar to those used for chip resistors and chip capacitors.

**COOPER** Bussmann



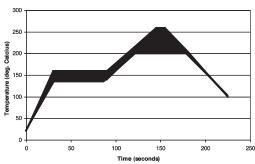
# Bussmann<sup>\*</sup>

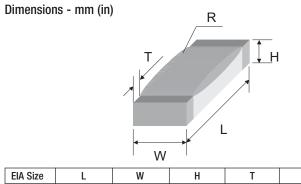
### **Environmental Specifications:**

- Moisture Resistance per EIA/IS-722 Paragraph 4.4.2. This standard is based upon MIL-STD-202G Method 103B but with temperature and relative humidity at +85°C and 85% RH respectively. Test condition 'A' (240Hr) per MIL-STD-202G.
- Thermal shock: MIL-STD-202, Method 107G, -55°C to 125°C, 30 min. cycle, 10 cycles.
- Vibration: MIL-STD-202F, Method 201A,(10 to 55 to 10 Hz, 1 min. cycle, 2 hrs each in X-Y-Z).
- Chemical resistance: ASTM D-543, 4 hrs @ 40°C, 3 solutions (H2O, detergent solution, defluxer).
- Operating temperature characteristics, measurement at +25°C, +105°C and -56°C.
- Full load voltage: 14.4Vdc, 18Vdc & 24Vdc for 1000 hrs, 25°C.
- Solder leach resistance and terminal adhesion: Per EIA-576.
- Solderability: MIL-STD-202, Method 208 (95% coverage).

#### **Soldering Recommendations**

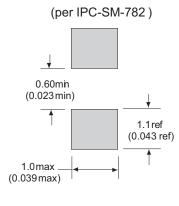
- · Compatible with lead and lead-free solder reflow processes
- Peak reflow temperatures and durations:
  - IR Reflow =  $260^{\circ}$ C max for 10 sec. max.
  - Wave Solder =  $260^{\circ}$ C max. for 10 sec. max.
- Recommended IR Reflow Profile:



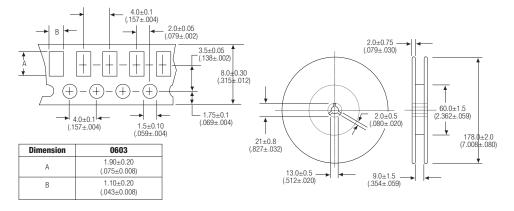


EIA Size	L	W	Н	Т	R
0603FSDA	1.60±0.10	0.80±0.10	0.50±0.10	0.30±0.20	0.70±0.10
	(0.063±0.004)	(0.031±0.004)	(0.020±0.004)	(0.012±0.008)	(0.028±0.004)

#### Recommended Pad Layout - in (mm)



#### Tape and Reel Specifications - mm (in)



The only controlled copy of this Data Sheet is the electronic read-only version located on the Cooper Bussmann Network Drive. All other copies of this document are by definition uncontrolled. This bulletin is intended to clearly present comprehensive product data and provide technical information that will help the end user with design applications. Cooper Bussmann reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Cooper Bussmann also reserves the right to change or update, without notice, any technical information contained in this bulletin. Once a product has been selected, it should be tested by the user in all possible applications.

Life Support Policy: Cooper Bussmann does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

